

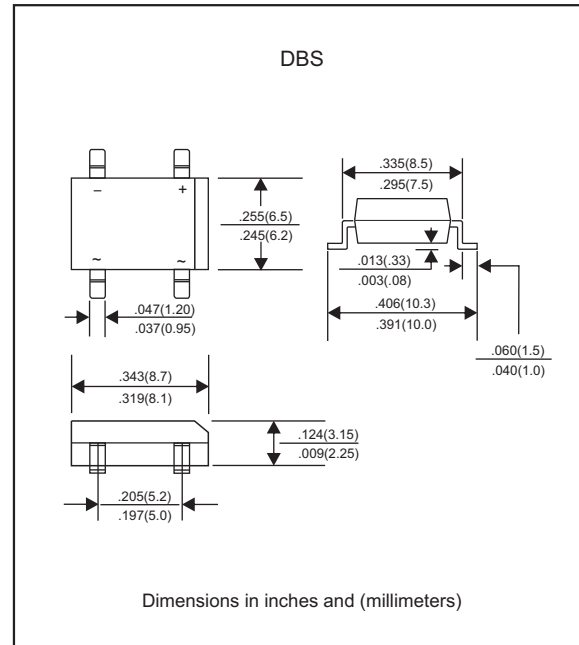
Features

- Rating to 1000V PRV
- Ideal for printed circuit board
- Low forward voltage drop,high current capability
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- The plastic material has UL flammability classification 94V-0

Mechanical data

- **Case:** DBS molded plastic body
- **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity:** As marked
- **Mounting Position:** Any

Package outline



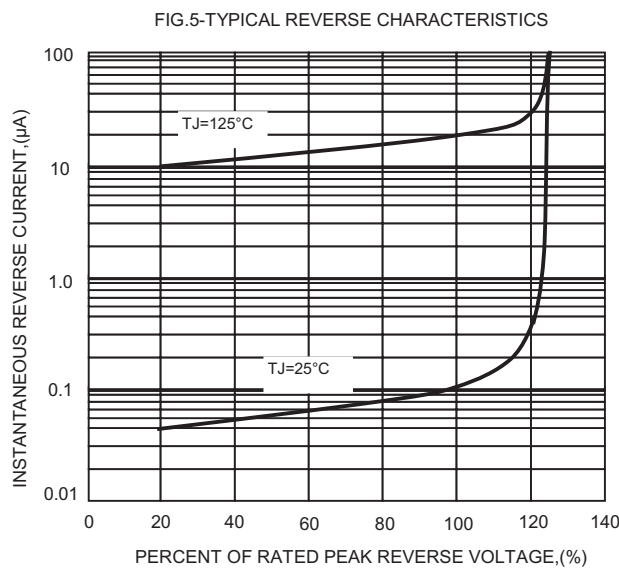
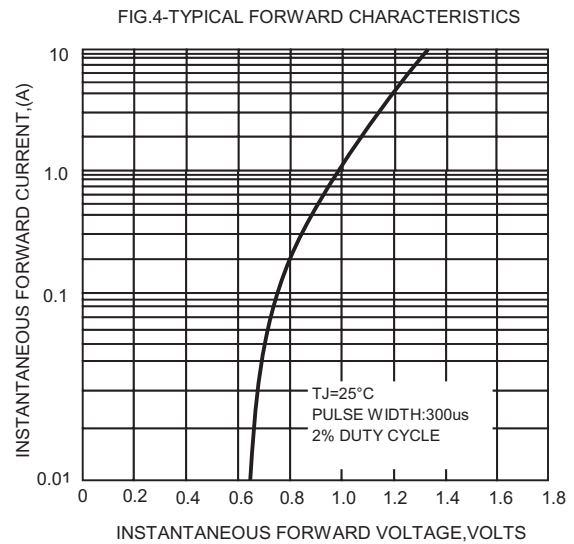
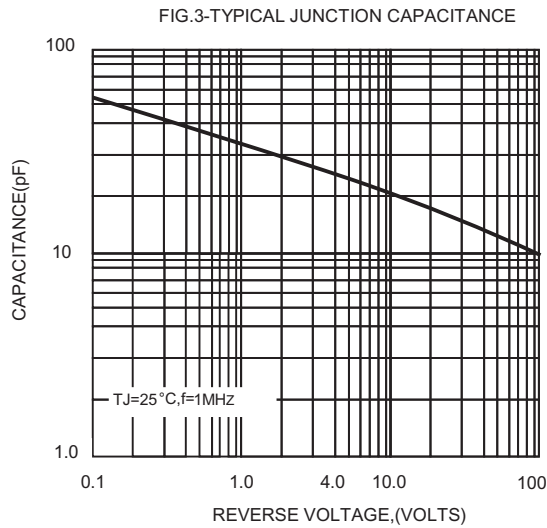
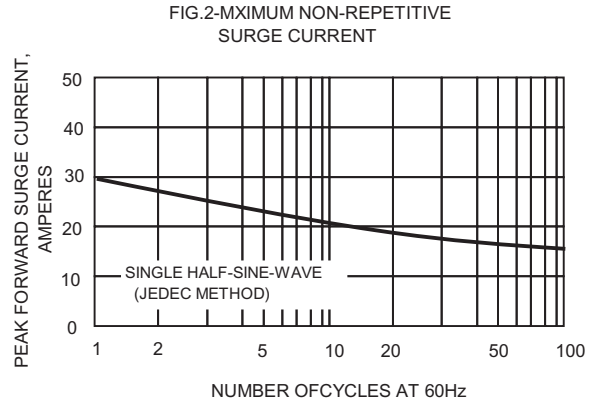
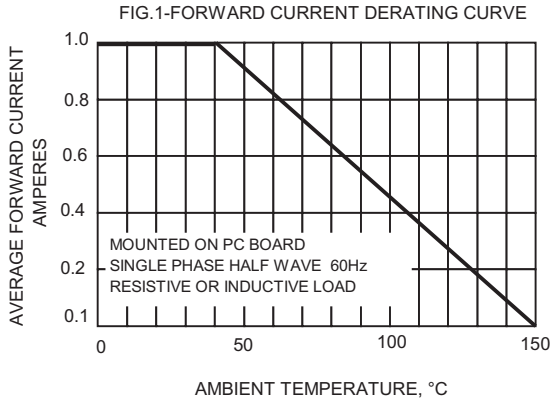
Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}C$ unless otherwise noted)

CHARACTERISTICS	SYMBOL	DB101S	DB102S	DB103S	DB104S	DB105S	DB106S	DB107S	UNIT
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ $T_A=40^{\circ}C$	I _(AV)	1.0							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I _{FSM}	30							A
Maximum Forward Voltage at 1.0A DC	V _F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_J=25^{\circ}C$ @ $T_J=125^{\circ}C$	I _R	10 500							μ A
I ² t Rating for Fusing(t<8.3ms)	I ² t	3.74							A ² s
Typical Junction Capacitance Per Element(Note1)	C _J	25							pF
Typical Thermal Resistance (Note2)	R _{θJA}	40							$^{\circ}C/W$
Operating Temperature Range	T _J	-55 to +150							$^{\circ}C$
Storage Temperature Range	T _{STG}	-55 to +150							$^{\circ}C$

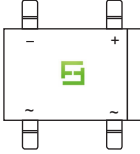
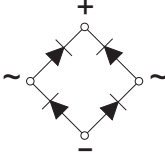
Note:1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC

2.Thermal resistance from junction to ambient mounted on P.C.B with 0.5*0.5"(13*13mm)copper pads.

Rating and characteristic curves



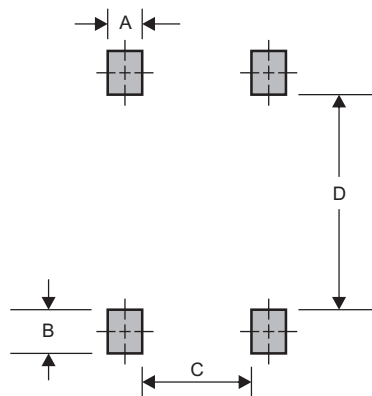
Pinning information

Simplified outline	Symbol
	

Marking

Type number	Marking code
DB101S	DB101S
DB102S	DB102S
DB103S	DB103S
DB104S	DB104S
DB105S	DB105S
DB106S	DB106S
DB107S	DB107S

Suggested solder pad layout

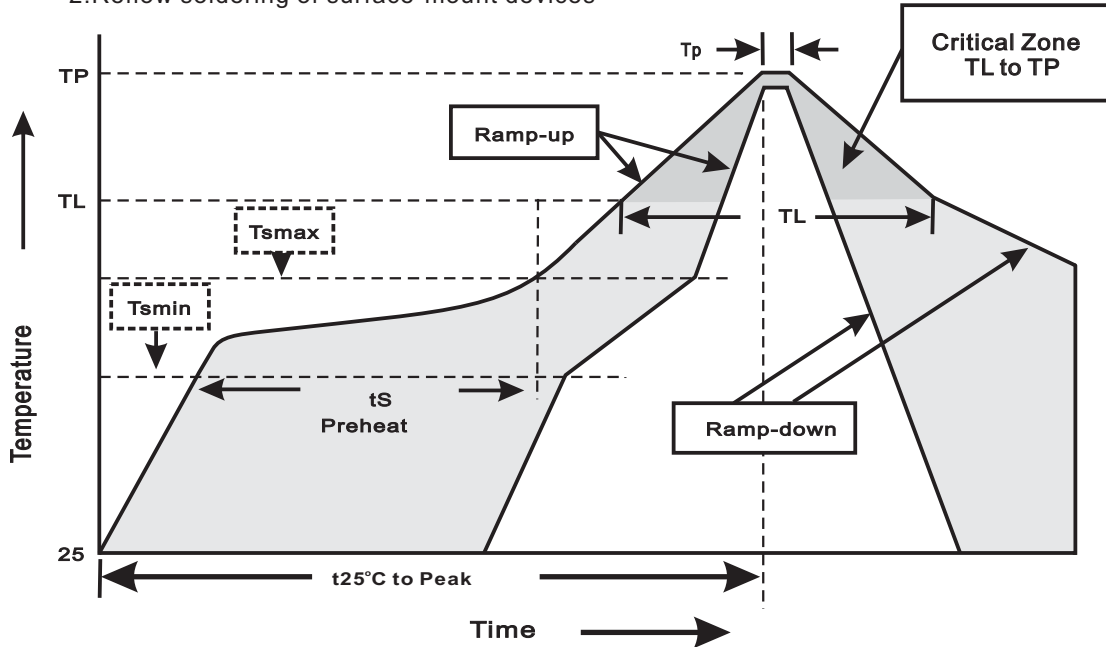


Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
DBS	0.059 (1.50)	0.047 (1.20)	0.157 (4.00)	0.291 (7.40)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmmin) -Temperature Max(Tsmmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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